

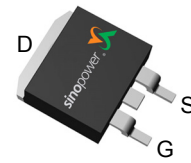
### Features

- 40V/120A  
 $R_{DS(ON)}=1.3m\Omega(max.)@V_{GS}=10V$   
 $R_{DS(ON)}=1.6m\Omega(max.)@V_{GS}=6V$
- 100% UIS +  $R_g$  Tested
- Reliable and Rugged
- Lead Free and Green Devices Available (RoHS Compliant)

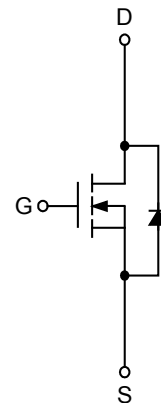
### Applications

- Brushed motor drive applications
- BLDC motor drive applications
- Battery powered circuits
- Half-bridge and full-bridge topologies
- Synchronous rectifier applications

### Pin Description

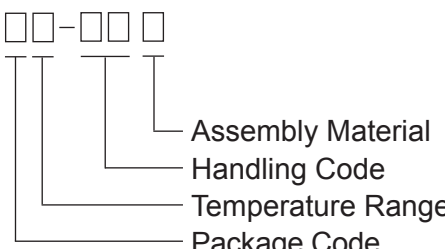



TO-263-2



N-Channel MOSFET

### Ordering and Marking Information

<p>SM4030NH □□-□□ □</p>  <p>Assembly Material Handling Code Temperature Range Package Code</p>	<p>Package Code G : TO-263-2</p> <p>Operating Junction Temperature Range C : -55 to 150 °C</p> <p>Handling Code TR : Tape &amp; Reel</p> <p>Assembly Material G : Halogen and Lead Free Device</p>
<p>SM4030NH G :</p>	 <p>XXXXX - Lot Code</p>

Note : SINOPOWER lead-free products contain molding compounds/die attach materials and 100% matte tin plate termination finish; which are fully compliant with RoHS. SINOPOWER lead-free products meet or exceed the leadfree requirements of IPC/JEDEC J-STD-020D for MSL classification at lead-free peak reflow temperature. SINOPOWER defines "Green" to mean lead-free (RoHS compliant) and halogen free (Br or Cl does not exceed 900ppm by weight in homogeneous material and total of Br and Cl does not exceed 1500ppm by weight).

SINOPOWER reserves the right to make changes to improve reliability or manufacturability without notice, and advise customers to obtain the latest version of relevant information to verify before placing orders.

**Absolute Maximum Ratings** ( $T_A=25^{\circ}\text{C}$  Unless Otherwise Noted)

Symbol	Parameter	Rating	Unit
<b>Common Ratings</b>			
$V_{DSS}$	Drain-Source Voltage	40	V
$V_{GSS}$	Gate-Source Voltage	$\pm 20$	
$T_J$	Maximum Junction Temperature	150	$^{\circ}\text{C}$
$T_{STG}$	Storage Temperature Range	-55 to 150	
$I_S$	Diode Continuous Forward Current	$T_C=25^{\circ}\text{C}$ 90	A
$I_D$	Continuous Drain Current	$T_C=25^{\circ}\text{C}$ 120 <sup>a</sup>	
	Continuous Drain Current	$T_C=100^{\circ}\text{C}$ 120 <sup>a</sup>	
$I_{DM}^b$	Pulsed Drain Current	$T_C=25^{\circ}\text{C}$ 400	
$P_D$	Maximum Power Dissipation	$T_C=25^{\circ}\text{C}$ 312	W
		$T_C=100^{\circ}\text{C}$ 125	
$R_{\theta JC}$	Thermal Resistance-Junction to Case	Steady State 0.4	$^{\circ}\text{C}/\text{W}$
$I_D$	Continuous Drain Current	$T_A=25^{\circ}\text{C}$ 33	A
		$T_A=70^{\circ}\text{C}$ 26	
$I_{DM}^b$	Pulsed Drain Current	$T_A=25^{\circ}\text{C}$ 132	
$P_D$	Maximum Power Dissipation	$T_A=25^{\circ}\text{C}$ 2.5	W
		$T_A=70^{\circ}\text{C}$ 1.6	
$R_{\theta JA}^c$	Thermal Resistance-Junction to Ambient	Steady State 50	$^{\circ}\text{C}/\text{W}$
$I_{AS}^d$	Avalanche Current, Single pulse	$L=0.5\text{mH}$ 60	A
$E_{AS}^d$	Avalanche Energy, Single pulse	$L=0.5\text{mH}$ 900	mJ

Note a : Max. continuous current is limited by bonding wire.

Note b : Pulse width limited by max. junction temperature.

Note c : Surface mounted on 1in2 pad area, steady state  $t = 999\text{s}$ .

Note d : UIS tested and pulse width limited by maximum junction temperature 150oC (initial temperature  $T_J=25\text{oC}$ ).

**Electrical Characteristics** ( $T_A = 25^\circ\text{C}$  unless otherwise noted)

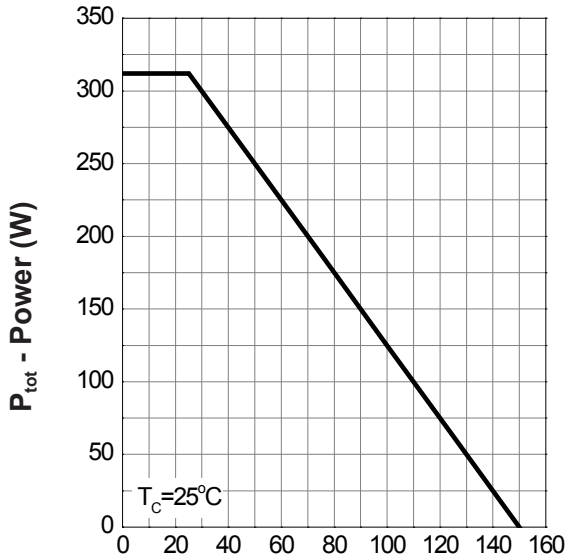
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_{DS}=250\mu A$	40	-	-	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=32V, V_{GS}=0V$	-	-	1	$\mu A$
		$T_J=85^\circ C$	-	-	30	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_{DS}=250\mu A$	2	3	4	V
$I_{GSS}$	Gate Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	$\pm 100$	nA
$R_{DS(ON)}^e$	Drain-Source On-state Resistance	$V_{GS}=10V, I_{DS}=40A$	-	1.05	1.3	m $\Omega$
		$V_{GS}=6V, I_{DS}=20A$	-	1.25	1.6	
Gfs	Forward Transconductance	$V_{DS}=5V, I_{DS}=20A$	-	75	-	S
<b>Diode Characteristics</b>						
$V_{SD}^e$	Diode Forward Voltage	$I_{SD}=20A, V_{GS}=0V$	-	0.75	1.1	V
$t_{rr}$	Reverse Recovery Time	$I_{SD}=40A, di_{SD}/dt=100A/\mu s$	-	90	-	ns
$t_a$	Charge Time		-	41	-	
$t_b$	Discharge Time		-	49	-	
$Q_{rr}$	Reverse Recovery Charge		-	118	-	
<b>Dynamic Characteristics<sup>f</sup></b>						
$R_G$	Gate Resistance	$V_{GS}=0V, V_{DS}=0V, F=1MHz$	-	2.5	-	$\Omega$
$C_{iss}$	Input Capacitance	$V_{GS}=0V,$ $V_{DS}=20V,$ Frequency=1.0MHz	-	15158	19706	pF
$C_{oss}$	Output Capacitance		-	4004	-	
$C_{rss}$	Reverse Transfer Capacitance		-	500	-	
$t_{d(ON)}$	Turn-on Delay Time	$V_{DD}=20V, R_L=20\Omega,$ $I_{DS}=1A, V_{GEN}=10V,$ $R_G=6\Omega$	-	54	98	ns
$t_r$	Turn-on Rise Time		-	38	69	
$t_{d(OFF)}$	Turn-off Delay Time		-	201	362	
$t_f$	Turn-off Fall Time		-	230	414	
<b>Gate Charge Characteristics<sup>f</sup></b>						
$Q_g$	Total Gate Charge	$V_{DS}=20V, V_{GS}=10V,$ $I_{DS}=40A$	-	197	275.8	nC
$Q_{gth}$	Threshold Gate Charge		-	46	-	
$Q_{gs}$	Gate-Source Charge		-	70	-	
$Q_{gd}$	Gate-Drain Charge		-	19	-	

Note e : Pulse test ; pulse width $\leq 300\mu s$ , duty cycle $\leq 2\%$ .

Note f : Guaranteed by design, not subject to production testing.

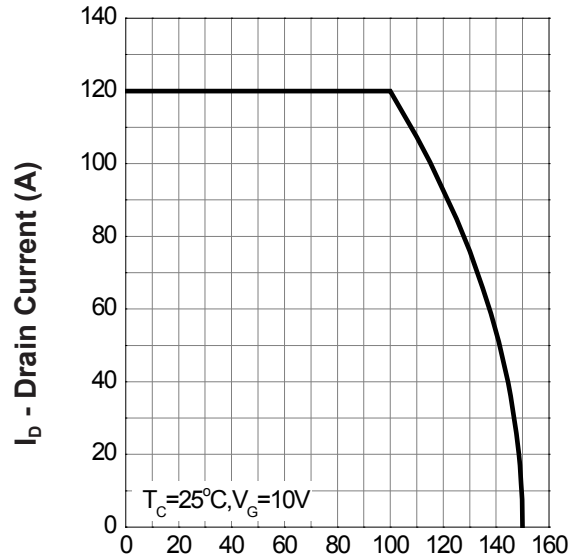
Typical Operating Characteristics

Power Dissipation



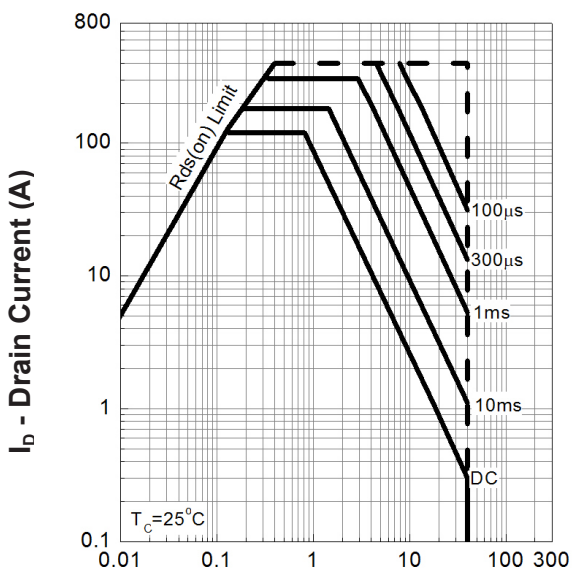
$T_j$  - Junction Temperature ( $^{\circ}\text{C}$ )

Drain Current



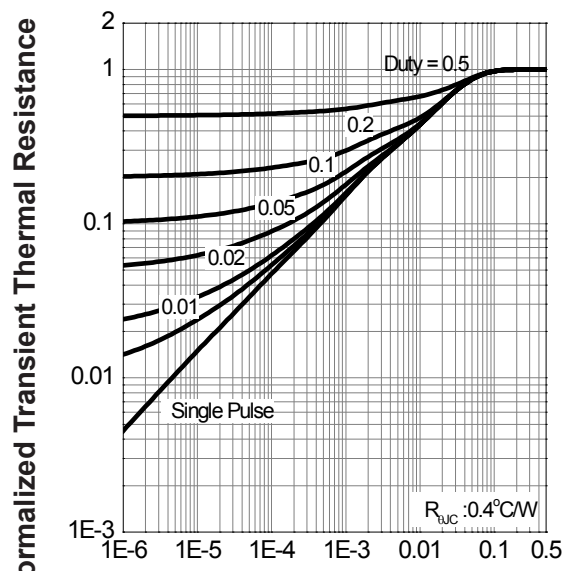
$T_j$  - Junction Temperature ( $^{\circ}\text{C}$ )

Safe Operation Area



$V_{DS}$  - Drain - Source Voltage (V)

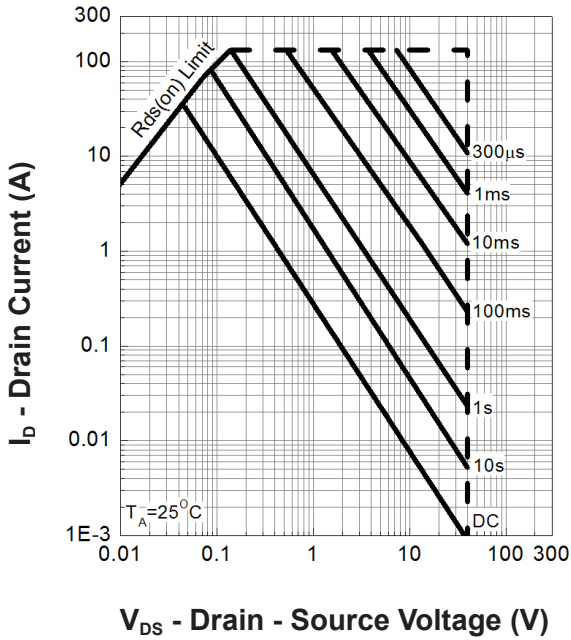
Thermal Transient Impedance



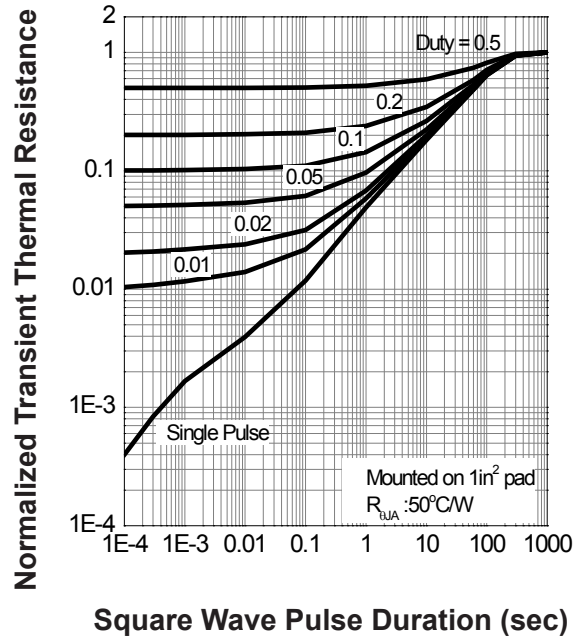
Square Wave Pulse Duration (sec)

Typical Operating Characteristics(Cont.)

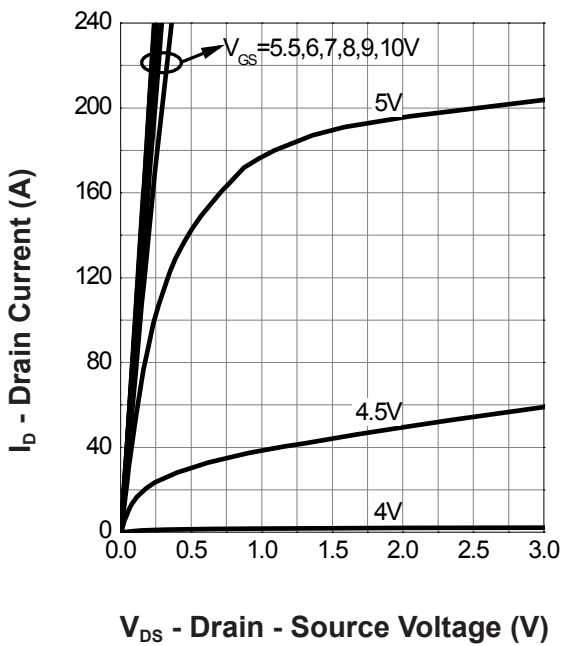
Safe Operation Area



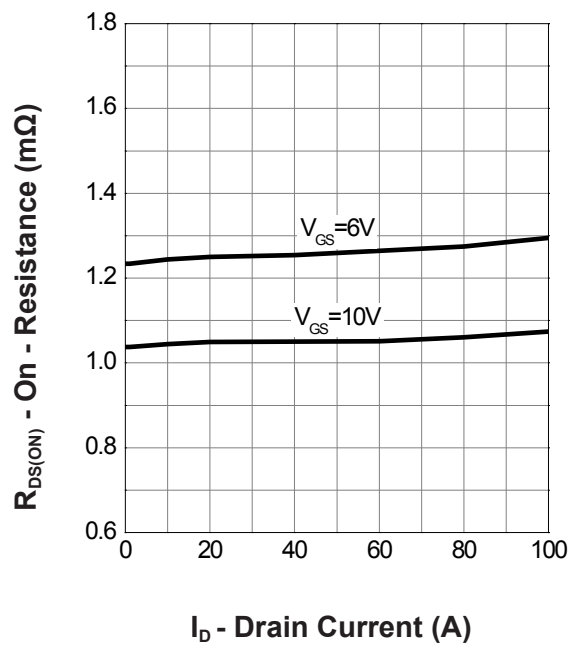
Thermal Transient Impedance



Output Characteristics

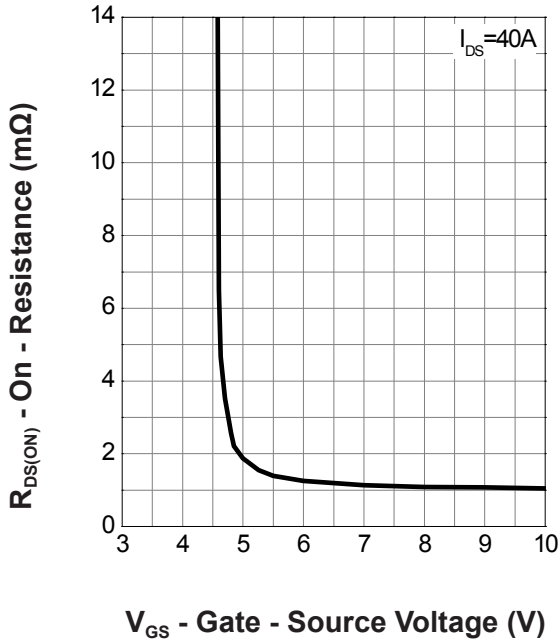


Drain-Source On Resistance

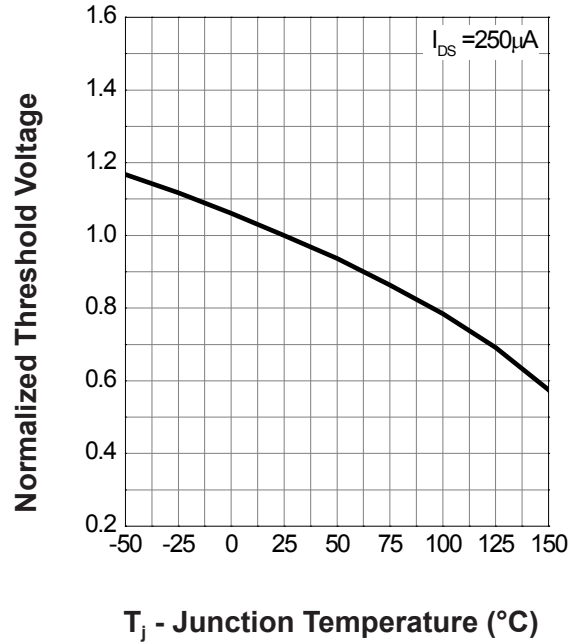


Typical Operating Characteristics(Cont.)

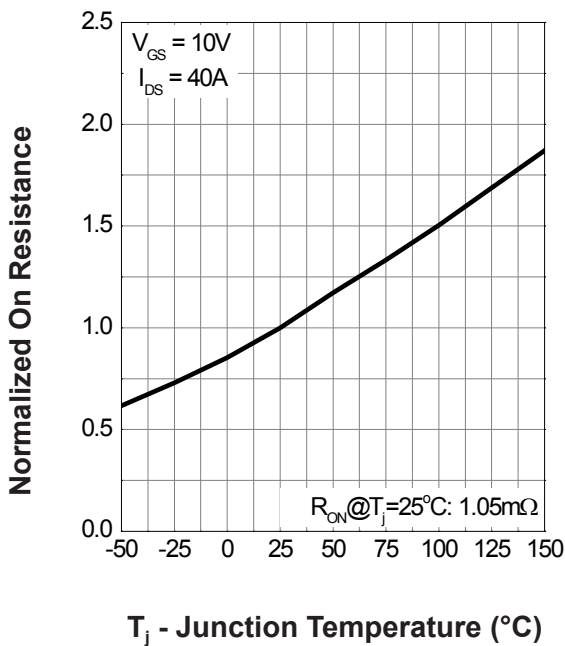
Gate-Source On Resistance



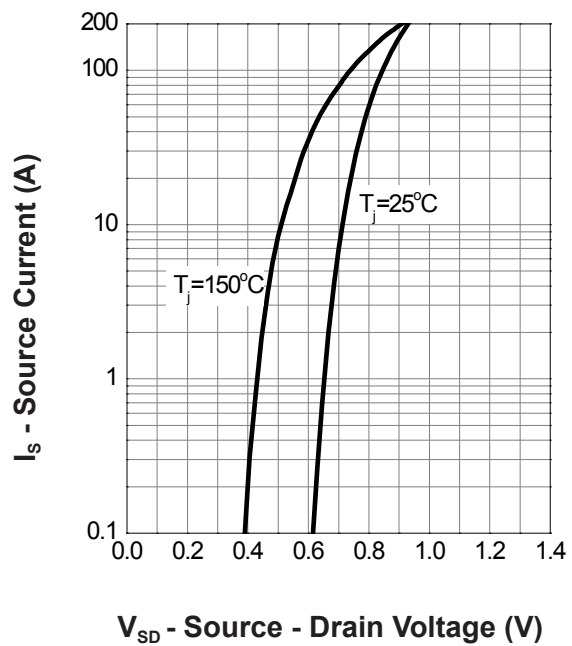
Gate Threshold Voltage



Drain-Source On Resistance

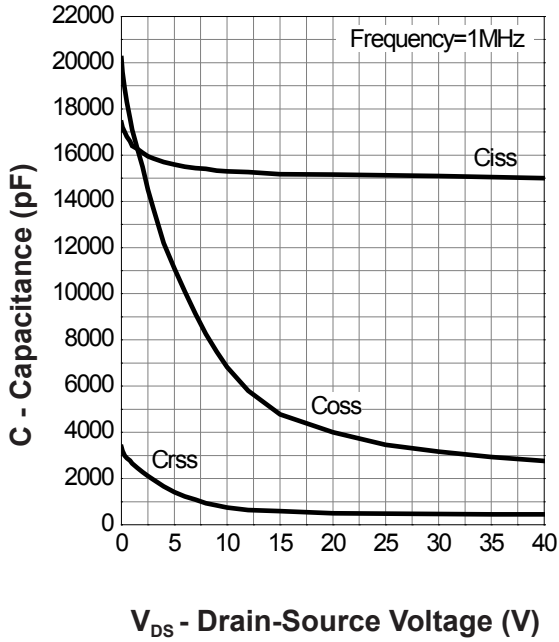


Source-Drain Diode Forward

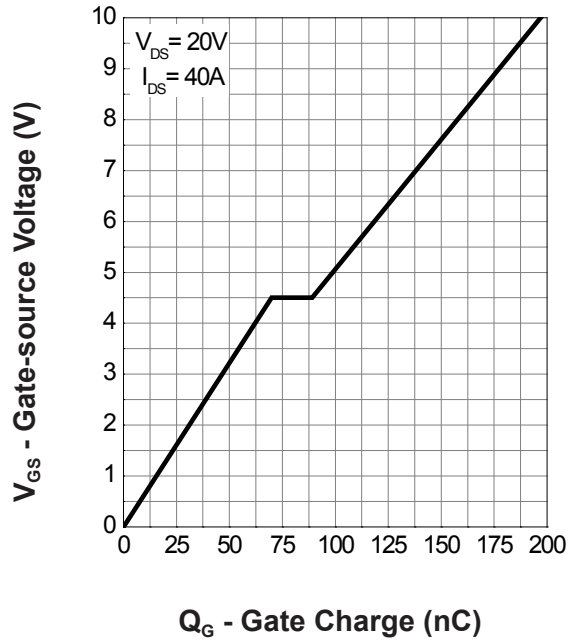


Typical Operating Characteristics(Cont.)

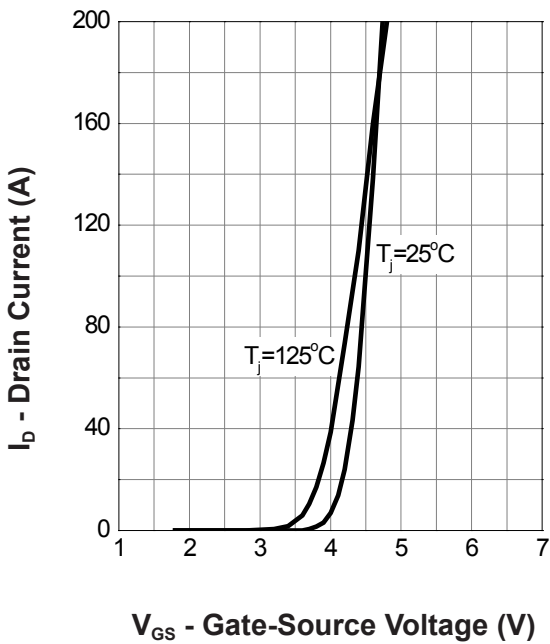
Capacitance



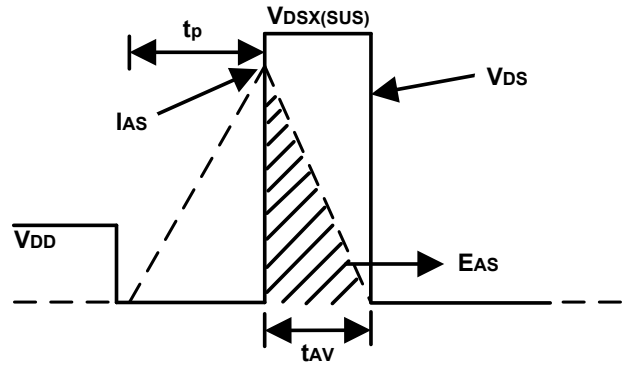
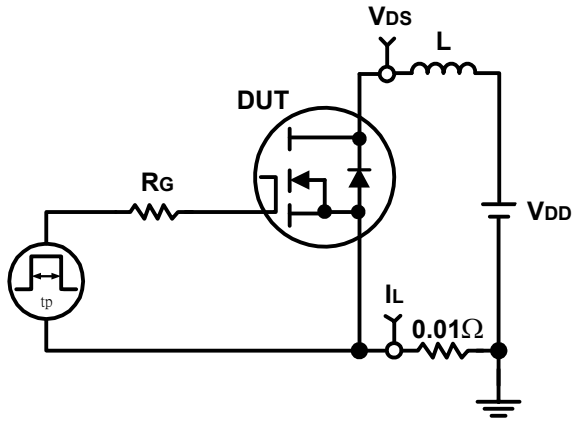
Gate Charge



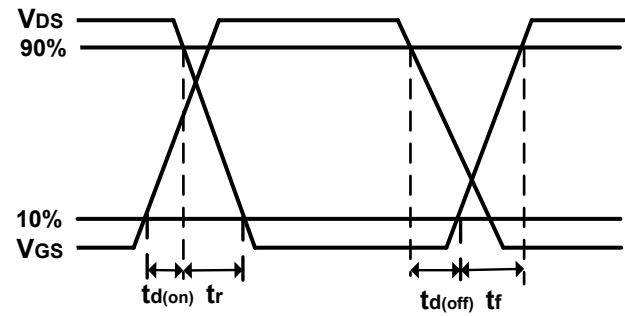
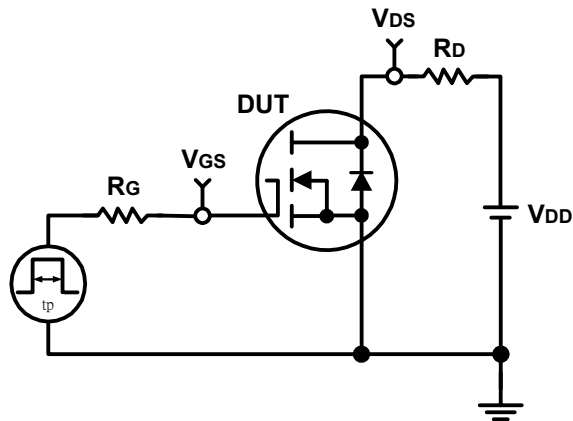
Transfer Characteristics



Avalanche Test Circuit and Waveforms



Switching Time Test Circuit and Waveforms





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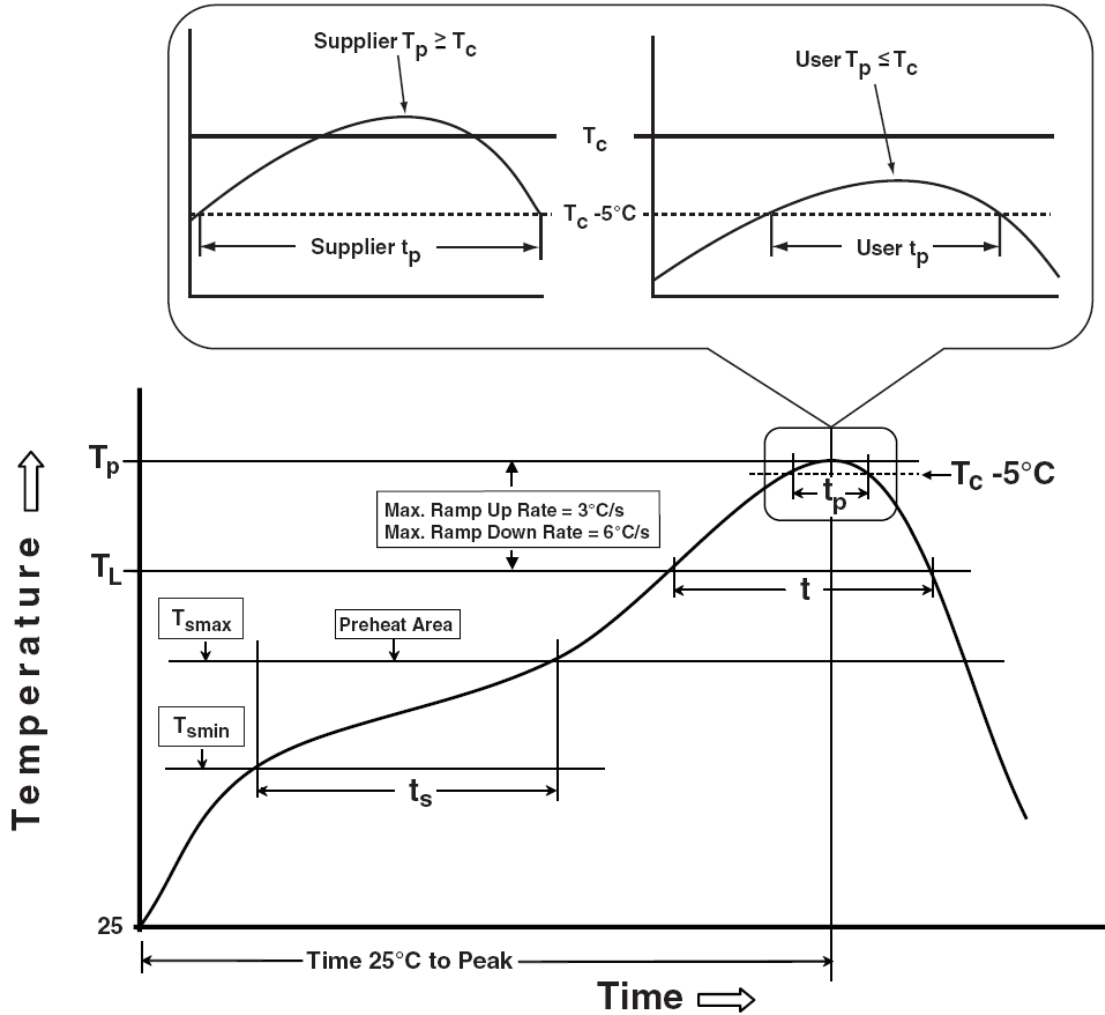
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Classification Profile



## Classification Reflow Profiles

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
<b>Preheat &amp; Soak</b>		
Temperature min ( $T_{smin}$ )	100 °C	150 °C
Temperature max ( $T_{smax}$ )	150 °C	200 °C
Time ( $T_{smin}$ to $T_{smax}$ ) ( $t_s$ )	60-120 seconds	60-120 seconds
Average ramp-up rate ( $T_{smax}$ to $T_p$ )	3 °C/second max.	3°C/second max.
Liquidous temperature ( $T_L$ )	183 °C	217 °C
Time at liquidous ( $t_L$ )	60-150 seconds	60-150 seconds
Peak package body Temperature ( $T_p$ )*	See Classification Temp in table 1	See Classification Temp in table 2
Time ( $t_p$ )** within 5°C of the specified classification temperature ( $T_c$ )	20** seconds	30** seconds
Average ramp-down rate ( $T_p$ to $T_{smax}$ )	6 °C/second max.	6 °C/second max.
Time 25°C to peak temperature	6 minutes max.	8 minutes max.
* Tolerance for peak profile Temperature ( $T_p$ ) is defined as a supplier minimum and a user maximum.		
** Tolerance for time at peak profile temperature ( $t_p$ ) is defined as a supplier minimum and a user maximum.		

Table 1. SnPb Eutectic Process – Classification Temperatures ( $T_c$ )

Package Thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> ≥350
<2.5 mm	235 °C	220 °C
≥2.5 mm	220 °C	220 °C

Table 2. Pb-free Process – Classification Temperatures ( $T_c$ )

Package Thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> 350-2000	Volume mm <sup>3</sup> >2000
<1.6 mm	260 °C	260 °C	260 °C
1.6 mm – 2.5 mm	260 °C	250 °C	245 °C
≥2.5 mm	250 °C	245 °C	245 °C

## Reliability Test Program

Test item	Method	Description
SOLDERABILITY	JESD-22, B102	5 Sec, 245°C
HTRB	JESD-22, A108	1000 Hrs, 80% of VDS max @ $T_{jmax}$
HTGB	JESD-22, A108	1000 Hrs, 100% of VGS max @ $T_{jmax}$
PCT	JESD-22, A102	168 Hrs, 100%RH, 2atm, 121°C
TCT	JESD-22, A104	500 Cycles, -65°C~150°C

## Customer Service

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